

Title (en)

METHOD FOR JOINING ALIGNED DISCRETE OPTICAL ELEMENTS

Title (de)

VERFAHREN ZUM FÜGEN JUSTIERTER DISKRETER OPTISCHER ELEMENTE

Title (fr)

PROCÉDÉ POUR JOINDRE DES ÉLÉMENTS OPTIQUES DISCRETS AJUSTÉS

Publication

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Application

EP 08700854 A 20080108

Priority

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Abstract (en)

[origin: WO2008083676A1] The invention relates to a method for joining aligned discrete optical elements. The object of the invention is to provide a method by means of which the optical elements can be joined in the aligned state, wherein a thermal connection having long-term stability can be produced at little expense and with high positioning accuracy. Surface regions to be joined to the optical element can be provided with at least one thin metallic layer by means of the method according to the invention for joining aligned discrete optical elements, wherein the regions are subsequently wetted using a liquid solder in a contactless dosed manner. The solder that is free of flux is applied to the surface regions to be joined via a nozzle using a pressurized gas stream.

IPC 8 full level

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Citation (examination)

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